

Disclosed is a resin composition for semiconductor encapsulation, containing an epoxy resin (A), a curing agent (B), and an inorganic filler material (C), the epoxy resin (A) including an epoxy resin (A-1) represented by formula (1), and the epoxy resin (A-1) containing a component represented by the formula (1) in which $n \geq 1$, and a component (a1) represented by the formula (1) in which $n = 0$ (wherein in the formula (1), R1 represents a hydrocarbon group having 1 to 6 carbon atoms; R2 represents a hydrocarbon group having 1 to 6 carbon atoms, or an aromatic hydrocarbon group having 6 to 14 carbon atoms, while R1s and R2s may be respectively identical with or different from each other; a represents an integer from 0 to 4; b represents an integer from 0 to 4; and n represents an integer of 0 or larger).

